

VCP 垂直連續電鍍銅設備

VERTICAL CONTINUOUS COPPER PLATING EQUIPMENT



新型第205620號

特色 / FEATURES

- 適用於印刷電路板，一次銅及二次銅電鍍製程
- 可全線自動化上板及下板，節省人力成本
- 板件厚度由0.046 ~6.0 mm不須框架及治具輔助生產
- 品質一致的鍍層厚度均勻性
- 高縱橫比之通孔、盲孔、填盲孔、填通孔分佈力有傑出的表現
- 模組化設計適合各種製程及產能需求
- 線內自動藥水剝掛
- 容易操作及維護
- Apply to panel and pattern plating
- Fully auto. loading/unloading, save manpower
- No auxiliary frame and jig to be used for board thickness 0.046~ 6.0 mm during production
- Uniform distribution of plating quality
- Remarkable throwing power of high aspect ratio for through hole, blind via, via filling and through hole filling
- Modular design fulfill customer's requirement
- Auto. online chemical stripping
- Easy operation and maintenance

規格 / SPECIFICATION

- 板片尺寸：24"x24" (max.); 16"x14" (min.)
32"x24" (max.); 24"x14" (min.) (選擇)
- 板片厚度：0.046 ~ 6.0 mm
- 線速度：0.3 ~ 1.5 m/min (可調)
- 電鍍視窗：610 (810) x 4800 mm/Chamber
- 銅缸數：1~6 (選擇)
- 電流密度：40 ASF (max.) for DC Rectifier
80 ASF (max.) for PPR Rectifier
- 陽極型式：不溶性氧化鈦陽極
- 陰極型式：垂直單邊挾持方式
- Panel size: 24"x24" (max.); 16"x14" (min.)
32"x24" (max.); 24"x14" (min.) (Option)
- Board thickness: 0.046 ~ 6.0 mm
- Line speed: 0.3 ~ 1.5 m/min (adjustable)
- Plating window: 610(810) x 4800 mm/Chamber
- Plating cell : 1~6 Chamber (Option)
- Current density: 40 ASF (max.) for DC Rectifier
80 ASF (max.) for PPR Rectifier
- Anode: Insoluble anode (Ti mesh with IrO₂ coating)
- Cathode: Vertical clamping system

總公司 Headquarter

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2025.10.發行

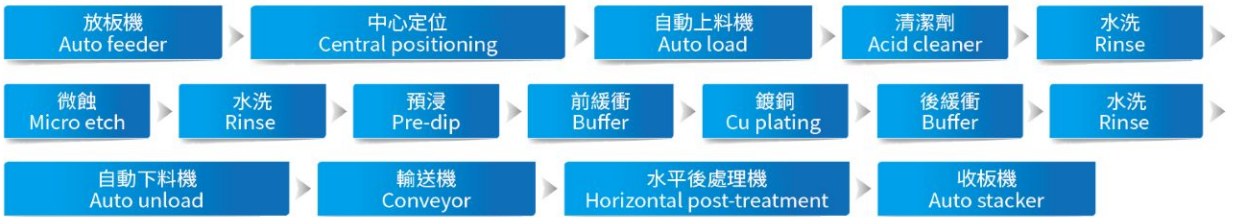
VCP(DT) 垂直連續電鍍銅設備(雙列型)

VERTICAL CONTINUOUS COPPER PLATING EQUIPMENT(DOUBLE TYPE)



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流程 / PROCESS



PERFORMANCE COPPER THICKNESS DISTRIBUTION

Within 15 mm boundary	Plating thickness (mil)	Standard deviation σ (mil)	Distribution $3\sigma / X\text{mean} \times 100\%$	Range Th.(Max.-Min.)(mil)
	1	0.025 ~ 0.04	$\leq 10\%$	0.15 ~ 0.25

THROWING POWER OF THROUGH HOLE(PPR)

	BGA-1	BGA-2	Isolated
C.D. (ASD)	4		
Board thickness (mm)	1.5		
Hole diameter (mm)	0.15		
A/R	8		
TP	103%	107%	114%

	BGA-1	BGA-2	BGA-3
C.D. (ASD)	1.2		
Board thickness (mm)	3.8		
Hole diameter (mm)	0.25		
A/R	15.2		
TP	114%	113%	116%

	BGA-1	BGA-2	Isolated
C.D. (ASD)	1.4		
Board thickness (mm)	4.6		
Hole diameter (mm)	0.2	0.2	0.5
A/R	23	23	9.2
TP	105%	103%	99%

